

CHINTEK TECHNOLOGY CO., LTD

Build PCB parameter

1. Pad Surface treatment : ☒ HASL ☐ ENIG ☐ ENIS ☐ OSP
2. Substrate Material : ☒ FR4 ☐ FR5 ☐ Aluminum ☐ _____
3. Single PCB Size : (**94** mm) x (**54** mm)
4. Layer : ☐ 2L ☒ 4L ☐ 6L ☐ 8L ☐ others : _____
5. Thickness Of Board : ☐ 1.0mm ☐ 1.2mm ☒ 1.6mm ☐ 2.0mm ☐ _____ mm
6. Copper Thickness : ☒ Standard(1oz) ☐ Specify (Inner layer _____ oz , Outer layer _____ oz)
 $1/3 \text{ oz} = 0.46\text{mil} = 12\mu''$
 $H \text{ oz} = 0.7\text{mil} = 18\mu''$
 $1 \text{ oz} = 1.4\text{mil} = 35\mu''$
7. Solder Mask color : ☒ Green ☐ Yellow ☐ Blue ☐ Black ☐ Red ☐ _____
8. Block Via hole : ☒ YES ☐ NO
9. Silkscreen color : ☒ White ☐ Black ☐ _____
10. UL Mark (UL Logo/E Number/ Fireproof rank) : ☐ YES ☒ NO
11. Date Code Format : ☒ Year / Week ☐ Week / Year ☐ NO
12. Panel layout : ☒ as per PCB maker design ☐ specific design As follows :
Drawing layout hereunder :